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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

U.S. Patent Appl. : 10/514,412
Applicant : Da Silvo Neto et al.
Filed : Nov. 15. 2004
Title : Variable Field Device for Process Automation
TC/A.U. : 2112
Examiner : H. Singh
Docket No. : DASI3001/FJD
Customer No. : 23364

Response to Notification of Non-Compliant Appeal Brief

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Attached is a copy of corrected page 2 of the Appeal Brief identifying claims 10-19 as the claims which are subject to this appeal.

Respectfully submitted,
BACON & THOMAS, PLLC

Date: April 17, 2009

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U.S. Pat. Appl. 09/270,673

STATUS OF CLAIMS

(37 CFR 41.37(c)(1)(iii))

Claims 10 - 19 are pending in this application.

Claims 10 - 19 have been finally rejected, and are the subject of this appeal.

Claims 1 - 9 as originally filed have been cancelled.

STATUS OF AMENDMENTS

(37 CFR 41.37(c)(1)(iv))

No amendment was filed after issuance of the Office Action of July 8, 2008.

SUMMARY OF CLAIMED SUBJECT MATTER

(37 CFR 41.37 (c)(1)(v))

(References are to page and line of the specification)

The invention on this appeal relates to a variable field device for process automation (pg. 1, lines 1 and 2). The field device is normally composed of various hardware components, which determined the functionality of the field device. Different field devices have different hardware components (pg. 2, lines 25 - 32). This multiplicity of components means a considerable expense in manufacture, since a multitude of hardware components has to be available (pg. 3, lines 3- 5).

The essential idea of the invention is that various modules of the field device are in the form of reprogrammable chips. (Pg. 4, lines 1 - 5). These chips in the form of units are each unique. See, for example, Fig. 2, which shows a sensor S1 which includes a measurement transducer MT, which is connected with a sensor unit SU. The sensor unit SU is followed by a digital signal processor DSP. The digital signal processor DSP is connected with a system